



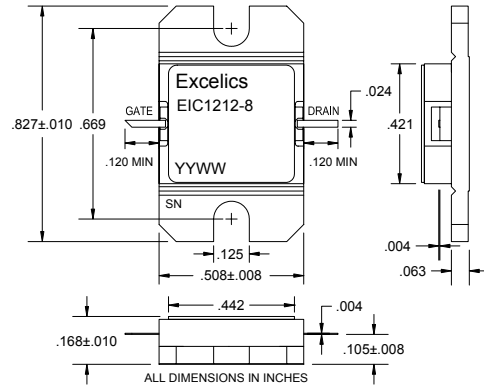
# EIC1212-8

UPDATED 01/04/2006

## 12.20-12.70 GHz 8-Watt Internally Matched Power FET

### FEATURES

- 12.20– 12.70GHz Bandwidth
- Input/Output Impedance Matched to 50 Ohms
- +39.0 dBm Output Power at 1dB Compression
- 6.5 dB Power Gain at 1dB Compression
- 27% Power Added Efficiency
- -46 dBc IM3 at PO = 28.5 dBm SCL
- Hermetic Metal Flange Package
- 100% Tested for DC, RF, and  $R_{TH}$



### ELECTRICAL CHARACTERISTICS ( $T_a = 25^\circ\text{C}$ )



Caution! ESD sensitive device.

| SYMBOL     | PARAMETERS/TEST CONDITIONS <sup>1</sup>  | MIN  | TYP  | MAX       | UNITS              |
|------------|--|------|------|-----------|--------------------|
| $P_{1dB}$  | Output Power at 1dB Compression $f = 12.20-12.70\text{GHz}$<br>$V_{DS} = 10\text{ V}$ , $I_{DSQ} \approx 2200\text{mA}$  | 38.5 | 39.0 |           | dBm                |
| $G_{1dB}$  | Gain at 1dB Compression $f = 12.20-12.70\text{GHz}$<br>$V_{DS} = 10\text{ V}$ , $I_{DSQ} \approx 2200\text{mA}$  | 5.5  | 6.5  |           | dB                 |
| $\Delta G$ | Gain Flatness $f = 12.20-12.70\text{GHz}$<br>$V_{DS} = 10\text{ V}$ , $I_{DSQ} \approx 2200\text{mA}$  |      |      | $\pm 0.6$ | dB                 |
| PAE        | Power Added Efficiency at 1dB Compression $f = 12.20-12.70\text{GHz}$<br>$V_{DS} = 10\text{ V}$ , $I_{DSQ} \approx 2200\text{mA}$  |      | 27   |           | %                  |
| $I_{d1dB}$ | Drain Current at 1dB Compression $f = 12.20-12.70\text{GHz}$   |      | 2300 | 2600      | mA                 |
| IM3        | Output 3rd Order Intermodulation Distortion<br>$\Delta f = 10\text{ MHz}$ 2-Tone Test; $P_{out} = 28.5\text{ dBm S.C.L}^2$<br>$V_{DS} = 10\text{ V}$ , $I_{DSQ} \approx 65\% IDSS$ $f = 12.70\text{GHz}$ | -43  | -46  |           | dBc                |
| $I_{DSS}$  | Saturated Drain Current $V_{DS} = 3\text{ V}$ , $V_{GS} = 0\text{ V}$  |      | 4000 | 5000      | mA                 |
| $V_P$      | Pinch-off Voltage $V_{DS} = 3\text{ V}$ , $I_{DS} = 40\text{ mA}$  |      | -2.5 | -4.0      | V                  |
| $R_{TH}$   | Thermal Resistance <sup>3</sup>  |      | 3.5  | 4.0       | $^\circ\text{C/W}$ |

Note: 1) Tested with 100 Ohm gate resistor.

2) S.C.L. = Single Carrier Level.

3) Overall  $R_{th}$  depends on case mounting.

### ABSOLUTE MAXIMUM RATING<sup>1,2</sup>

| SYMBOL    | CHARACTERISTIC          | VALUE                     |
|-----------|-------------------------|---------------------------|
| $V_{DS}$  | Drain to Source Voltage | 10 V                      |
| $V_{GS}$  | Gate to Source Voltage  | -4.5 V                    |
| $I_{DS}$  | Drain Current           | $IDSS$                    |
| $I_{GSF}$ | Forward Gate Current    | 80 mA                     |
| $P_{IN}$  | Input Power             | @ 3dB compression         |
| $P_T$     | Total Power Dissipation | 38 W                      |
| $T_{CH}$  | Channel Temperature     | 175 $^\circ\text{C}$      |
| $T_{STG}$ | Storage Temperature     | -65/+175 $^\circ\text{C}$ |

Notes:

1. Operating the device beyond any of the above ratings may result in permanent damage or reduction of MTTF.

2. Bias conditions must also satisfy the following equation  $P_T < (T_{CH} - T_{PKG})/R_{TH}$ ; where  $T_{PKG}$  = temperature of package, and  $P_T = (V_{DS} * I_{DS}) - (P_{OUT} - P_{IN})$ .

Specifications are subject to change without notice.

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